

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ravi Nalla</td> <td>10/10/2012</td> </tr> <tr> <td>Omar Bchir</td> <td>10/22/2012</td> </tr> <tr> <td>Houssam Jomaa</td> <td>10/22/2012</td> </tr> </tbody> </table>		Name	Execution Date	Ravi Nalla	10/10/2012	Omar Bchir	10/22/2012	Houssam Jomaa	10/22/2012		
Name	Execution Date										
Ravi Nalla	10/10/2012										
Omar Bchir	10/22/2012										
Houssam Jomaa	10/22/2012										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Blvd</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95054</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Blvd	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95054
Name:	Intel Corporation										
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12059031</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12059031						
Property Type	Number										
Application Number:	12059031										
CORRESPONDENCE DATA											
Fax Number:	6123393061										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	612-373-6900										
Email:	saustin@slwip-rc.com										
Correspondent Name:	Schwegman, Lundberg, & Woessner P.A.										
Address Line 1:	PO Box 2938										
Address Line 4:	Minneapolis, MINNESOTA 55402										
ATTORNEY DOCKET NUMBER:	884.L10US1										
NAME OF SUBMITTER:	Sally Austin										
<p>Total Attachments: 11 source=884L10US1ASSNXMITsigned#page1.tif source=884L10US1ASSNXMITsigned#page2.tif</p>											

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RECORDATION FORM COVER SHEET
PATENTS ONLY

Atty Ref/Docket No.: 884.L10US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Ravi Nalla, Omar Bchir, Houssam Jomaa

Additional name(s) of conveying party(ies) attached?

[] Yes [X] No

3. Nature of conveyance:

[X] Assignment

[] Merger

[] Security Agreement [] Change of Name

[] Other

Execution Date: October 10, 2012, October 22, 2012,
October 22, 2012

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054

Country: United States of America

Additional name(s) & address(es) attached? [] Yes [X] No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Serial No. 12/059,031, filed March 31, 2008

Additional numbers attached? [] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David C. Peterson

Address:

Schwegman, Lundberg & Woessner, P.A.

P.O. Box 2938

Minneapolis, MN 55402--0938

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

[] Enclosed

[X] Authorized to be charged to deposit account
19-0743

8. Please charge any additional fees or credit any over payments to our Deposit Account No.: 19-0743


DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David C. Peterson/Reg. No. 47,857

Name of Person Signing


Signature

11/30/2012

Date

Total number of pages including cover sheet: 11

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks

Mail Stop Assignment Recordation Services

P.O. Box 1450

Alexandria, VA 22313-1450

PATENT
REEL: 029393 FRAME: 0307

ASSIGNMENT

WHEREAS, Ravi Nalla, Omar Bchir, Houssam Jomaa (hereinafter the "Undersigned") have made one or more inventions and other subject matter (hereinafter collectively referred to as the "Invention") which are described in a patent application filed on March 31, 2008, which application was assigned US patent application serial number 12/059,031, and which is titled MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged by the Undersigned, the Undersigned do hereby irrevocably and unconditionally:

CONVEY, ASSIGN, AND TRANSFER to Intel Corporation (the "Assignee"), a corporation of the State of Delaware, having a place of business at 2200 Mission College Blvd., Santa Clara, CA 95054, the Undersigned's entire right, title, and interest for the United States and all foreign countries and jurisdictions in and to:

the Invention which is disclosed in the above-identified application or applications;
such application or applications, and all divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other applications for a patent or patents which have been or shall be filed in the United States (including all provisional and non-provisional applications), and in all foreign countries and jurisdictions based in whole or in part on any of such Invention (including any application for a utility model or an innovation patent application);

all original and reissued patents which have been or shall be issued in the United States and all foreign countries and jurisdictions based in whole or in part on any of such Invention;

including the right to claim priority to the above-identified patent application or applications in relation to subject matter based in whole or in part on the above-identified patent application or applications and any of the foregoing including the right to file foreign applications under the provisions of any convention or treaty;

and including the right to all causes of action, remedies, and other enforcement rights related to the above-identified application or applications, including without limitation the right to sue for past, present, or future infringement, misappropriation, or violation of any and all rights related to the above-identified patent application or applications and any of the foregoing, including the right to obtain and collect damages for past, present, or future infringement;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such Invention to the Assignee;

AUTHORIZE AND REQUEST that any attorney associated with U.S. Patent and Trademark Office (USPTO) Customer No. 45457 may (directly or through his/her designee) delete, insert, or alter any information related to the above-identified patent application or applications or any of the foregoing, after execution of this Assignment;

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

Page 2 of 5

Docket No: 884.L10US1

Client Ref. No. P26726

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or shall be made to others by the Undersigned, and that the full right to convey the same as herein expressed is possessed by the Undersigned;

COVENANT, that when requested and without compensation, but at the expense of the Assignee, in order to carry out in good faith the intent and purpose of this Assignment, the Undersigned shall (1) execute all provisional, non-provisional, divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other patent applications for the Invention; (2) execute all rightful oaths, declarations, assignments, powers of attorney and other papers for the Invention; (3) communicate to the Assignee all facts known to the Undersigned relating to the Invention and the history thereof; (4) cooperate with the Assignee in any interference, reexamination, reissue, opposition, dispute, or litigation involving any of the applications or patents for the Invention; and (5) take such further actions as the Assignee shall reasonably consider necessary or desirable for vesting title to such Invention in the Assignee, or for securing, maintaining and enforcing proper patent protection for the Invention;

COVENANT, that should any provision of this agreement be held unenforceable by an authority of competent jurisdiction, such a ruling shall not affect the validity and enforceability of the remaining provisions. To the extent that any such provision is found to be unenforceable, the Undersigned, when requested and without compensation shall act in good faith to substitute for such provision a new provision with content and purpose as close as possible to the provision deemed unenforceable.

THIS AGREEMENT IS TO BE BINDING on the heirs, assigns, representatives, and successors of the Undersigned, and is to extend to the benefit of the successors, assigns, and nominees of the Assignee.

AGREED as of the date of my signature below:

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

Page 3 of 5

Docket No: 884.L10US1

Client Ref. No. P26726

Assignor:

(Signature): J. Ravi Kiran

Name: Ravi Nalla

City/State: SAN JOSE, CA

Date: 10/10/12

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

Page 4 of 5

Docket No: 884.L10US1

Client Ref. No. P26726

Assignor:

(Signature): _____

Name: Omar Bchir

City/State: _____

Date: _____

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

Page 5 of 5

Docket No: 884.L10US1

Client Ref. No. P26726

Assignor:

(Signature): _____

Name: Houssam Jomaa

City/State: _____

Date: _____

ASSIGNMENT

WHEREAS, Ravi Nalla, Omar Bchir, Houssam Jomaa (hereinafter the "Undersigned") have made one or more inventions and other subject matter (hereinafter collectively referred to as the "Invention") which are described in a patent application filed on March 31, 2008, which application was assigned US patent application serial number 12/059,031, and which is titled MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS.

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CONVEY, ASSIGN, AND TRANSFER to Intel Corporation (the "Assignee"), a corporation of the State of Delaware, having a place of business at 2200 Mission College Blvd., Santa Clara, CA 95054, the Undersigned's entire right, title, and interest for the United States and all foreign countries and jurisdictions in and to:

the invention which is disclosed in the above-identified application or applications;

such application or applications, and all divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other applications for a patent or patents which have been or shall be filed in the United States (including all provisional and non-provisional applications), and in all foreign countries and jurisdictions based in whole or in part on any of such invention (including any application for a utility model or an innovation patent application);

all original and reissued patents which have been or shall be issued in the United States and all foreign countries and jurisdictions based in whole or in part on any of such invention;

including the right to claim priority to the above-identified patent application or applications in relation to subject matter based in whole or in part on the above-identified patent application or applications and any of the foregoing including the right to file foreign applications under the provisions of any convention or treaty;

and including the right to all causes of action, remedies, and other enforcement rights related to the above-identified application or applications, including without limitation the right to sue for past, present, or future infringement, misappropriation, or violation of any and all rights related to the above-identified patent application or applications and any of the foregoing, including the right to obtain and collect damages for past, present, or future infringement;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such invention to the Assignee;

AUTHORIZE AND REQUEST that any attorney associated with U.S. Patent and Trademark Office (USPTO) Customer No. 45457 may (directly or through his/her designee) delete, insert, or alter any information related to the above-identified patent application or applications or any of the foregoing, after execution of this Assignment;

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

Page 2 of 3

Docket No. 888.L16US1

Client Ref. No. P26726

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COVENANT, that should any provision of this agreement be held unenforceable by an authority of competent jurisdiction, such a ruling shall not affect the validity and enforceability of the remaining provisions. To the extent that any such provision is found to be unenforceable, the Undersigned, when requested and without compensation shall act in good faith to substitute for such provision a new provision with content and purpose as close as possible to the provision deemed unenforceable.

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Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS.

Page 3 of 5

Docket No. 884,100US1

Client Ref. No. P26726

Assignor:

(Signature):

Name: Ravi Nalla

City/State:

Date:

Assignment

Assignors: Ravi Nalla et al.

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLS


Page: 4 of 5

Docket No: 884.1.10US1

Client Ref. No. P26726

Assignor:

(Signature):



Name:

Omar Bchir

City/State:

San Diego, CA

Date:

10/22/2012

Assignment

Assignors: Ravi Nalla et al

Title: MECHANICAL ADHESION OF COPPER METALLIZATION TO DIELECTRIC WITH PARTIALLY CURED EPOXY FILLERS

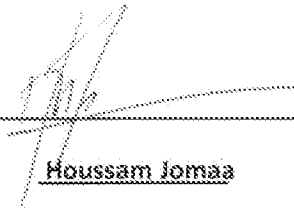
Page 5 of 5

Docket No: 884.L10US1

Client Ref. No. P26726

Assignor:

(Signature):



Name:

Houssam Jomaa

City/State:

San Diego, California

Date:

10/22/2012